Information & Control NA TC Chapter

Meeting Summary and Minutes

SEMICON West

Wednesday, October 8, 2025

9:00-12:00, 1:00-4:00 PM Mountain Time

TC Chapter Announcements

Next TC Chapter Meeting

Wednesday, February 11, 2026

9:00-12:00, 1:00-4:00 PM Pacific Time

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Co-Chairs: James Moyne (Applied Materials / University of Michigan), Brian Rubow (Cimetrix), Albert Fuchigami (PEER Group)
SEMI Staff: Michelle Sun

Company	*Last*	*First*	*Company*	*Last*	*First*
Agileo Automation	*Golra*	*Fahad*	Lam Research	Day	Roger
Applied Materials, Inc.	*Perevoztchikov*	*Konstantin*	Kontron-AIS GmbH	*Mueller*	*Bert*
Applied Materials, Inc.	Moyne	James	Micron Technology, Inc.	*Cicero*	*Jason*
Besi Austria GmbH	Meusburger	Peter	NAURA	*Cao*	*Clark*
Cimetrix	Weber	Alan	PEER Group Inc.	Fuchigami	Albert
Cimetrix Incorporated	Rubow	Brian	SCREEN Semiconductor Solutions Co., Ltd.	*Nishimura*	*Takayuki*
Cimetrix Incorporated	Tracey	Tami	SEMI	*Sun*	*Michelle*
Doople	*Kim*	*Hyungsu*	Tokyo Electron Kroea Ltd.	Min Im	Byoung
EWA-Canada	*Thomas*	*Nicholas*	Tokyo Electron Limited	Mochizuki	Tadashi
Hitachi High-Tech Corporation	*Toyoshima*	*Yuko*	Self	Howard	Richard
Intel Corp.	*Bond*	*Ryan*	SEMI	Sun	Michelle
Intel Corp.	*Maloney*	*Chris*	Industrial Strength Graphics International	*Summers*	*Frank*

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
Digital Twins Task Force **[New]**		James Moyne (U of Michigan)
Digital Twins Task Force **[New]**		Brian Rubow (PDF Solutions)
Digital Twins Task Force **[New]**		Chris Maloney (Intel)
Digital Twins Task Force **[New]**		Fahad Golra (Agileo Automation)
Sensor Bus TF	Dan Judd (Arlington Lab) [*stepped down*]	

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
	Digital Twins Task Force [**New**]

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
6743C	Revision to SEMI E95-1101, Specification for Human Interface for Semiconductor Manufacturing Equipment	**Passed**, Ratification Ballot to be issued
7178A	Revision to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata	**Failed**, to be discontinued
7321B	Line Item Revision to SEMI E120-0922 (Reapproved 0823) Specification for the Common Equipment Model (CEM), SEMI E120.2-0823 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-0923 Specification for Equipment Self Description (EqSD), SEMI E125.2-0923 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-0624 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-0624 Specification for Protocol Buffers for Equipment Client Authentication And Authorization (ECA), SEMI E134-0624 Specification for Data Collection Management, SEMI E134.2-0624 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-0624 Specification for Protocol Buffers Common Components	
LI-1	Add filtering capabilities and constraints for retrieving SEMI E125 metadata	**Passed**
LI-2	Update issues raised by TF members	**Passed** with editorial changes
7344	Line Item Revision to SEMI E192-0121 – Guide for Equipment Adoption Criteria for GEM and GEM-Related Standards	
LI-1	E192 Updates based on E157, E190, and E191	**Failed**
7345	Line Item Revision to SEMI E90-0624 - Specification for Substrate Tracking and SEMI E90.1-0624 - Specification for SECS-II Protocol Substrate Tracking	
LI-1	Report Batch Assembly and Disassembly	**Failed**
7346	Line Item Revision to SEMI E54.23-0520, Specification for Sensor/Actuator Network Communications for CC-Link®IE	
LI-1	Replace Biased Terms	**Passed** as balloted
LI-2	Updates to References, Trademarks and Other Editorial Changes	**Passed** as balloted
7376	Line Item Revision to SEMI E30-0125 - Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM), SEMI E30.1-0217 (Reapproved 0423) Specification for Inspection and Review Specific Equipment Model (ISEM)	
LI-1	Correct issues with SEMI E30 variables	**Passed** as balloted
7377	Line Item Revision to SEMI E40-0324 - Specification for Processing Management and SEMI E40.1-1218 (0324) Specification for SECS-II Protocol for Processing Management	
LI-1	Correct issues with SEMI E40 variables	**Passed** as balloted
7378	Line Item Revision to SEMI E87-0225 - Specification for Carrier Management (CMS) and SEMI E87.1-0225 - Specification for SECS-II Protocol for Carrier Management (CMS)	
LI-1	Correct issues with SEMI E87 variables	**Passed** as balloted
LI-2	Correct issues with BypassScanSlotMap functionality	**Passed** as balloted
7380	Line Item Revision to SEMI E142-0225 - Specification for Substrate Mapping, SEMI E142.1-0225 — Specification for XML Schema for Substrate Mapping,	

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
	SEMI E142.2-1016 (0225) — Specification for SECS II Protocol for Substrate Mapping, SEMI E142.3-1016 (0225) — Specification for Web Services for Substrate Mapping, SEMI E142.4-1022 (0225) — Specification for SECS II Protocol for Substrate Mapping Using Item Transfer	
LI-1	Add Well-Known Names to variables defined in SEMI E142.4	**Failed**
LI-2	Address issues raised by TF members	**Passed** with editorial changes
7382	Reapproval of SEMI E175-1116 - Specification for Subsystem Energy Saving Mode Communication (SESMC)	**Failed**, to be discontinued

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
7357	SNARF Approval	PCS	New Standard: Specification for Failure Analysis Reporting
7381	SNARF Approval	ABFI	Revision to Add a New Subordinate Standard: Specification for Transforming Non-E142 XY Coordinates to SEMI E142-0125: Specification for Substrate Mapping

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
7419	SNARF Approval	DDA	Line Item Revision to SEMI E120-0922 (Reapproved 0823) Specification for the Common Equipment Model (CEM), SEMI E120.2-1224 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1224 Specification for Equipment Self Description (EqSD), SEMI E125.2-1224 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-1224 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1224 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA), SEMI E134-1224 Specification for Data Collection Management, SEMI E134.2-1224 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1224 Specification for Protocol Buffers Common Components
7420	SNARF Approval	EDP	Line Item Revision to SEMI E190.1-1124 - Specification for Common Data for Etch Components

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
7421	SNARF Approval	EDA	Line Item Revision to SEMI E178-0120 Guide for EDA Freeze Version
7425	SNARF Approval	GEM300	Line Item Revision to SEMI E116-0324, Specification for Equipment Performance Tracking
7426	SNARF Approval	CDS	Line Item Revision to SEMI E191-1024 Specification for Computing Device Cybersecurity Status Reporting, and SEMI E191.1-1024 Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting
7427	SNARF Approval	GEM300	Line Item Revision to SEMI E172-0725, Specification for SECS Equipment Data Dictionary (SEDD)
7428	SNARF Approval	GEM300	Revision to Add a New Subordinate Standard: Specification for Secure High-Speed Secs Message Service (Secure-HSMS) to SEMI E37-0222 Specification for High-Speed SECS Message Services (HSMS) Generic Services

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
R6743C	Cycle 9-2025	GUI	Revision to SEMI E95-1101, Specification for Human Interface for Semiconductor Manufacturing Equipment
6926A	Cycle 1-2026	CDS	New Standard: Specification for Equipment Operator Access Management and Monitoring
7231	Cycle 1-2026	CDS	Revision to Add a New Subordinate Standard: Specification for Protocol Buffers for Computing Device Cybersecurity Status Reporting to Specification for Computing Device Cybersecurity Status Reporting
7344A	Cycle 1-2026	GEM300	Line Item Revision to SEMI E192-0121 – Guide for Equipment Adoption Criteria for GEM and GEM-Related Standards
7345A	Cycle 1-2026	GEM300	Line Item Revision to SEMI E90-0624 - Specification for Substrate Tracking and SEMI E90.1-0624 - Specification for SECS-II Protocol Substrate Tracking
7380A	Cycle 1-2026	ESEC	Line Item Revision to SEMI E142-0225 - Specification for Substrate Mapping, SEMI E142.1-0225 — Specification for XML Schema for Substrate Mapping, SEMI E142.2-1016 (0225) — Specification for SECS II Protocol for Substrate Mapping, SEMI E142.3-1016 (0225) — Specification for Web Services for Substrate Mapping, SEMI E142.4-1022 (0225) — Specification for SECS II Protocol for Substrate Mapping Using Item Transfer
7419	Cycle 1-2026	DDA	Line Item Revision to SEMI E120-0922 (Reapproved 0823) Specification for the Common Equipment Model (CEM), SEMI E120.2-1224 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1224 Specification for Equipment Self Description (EqSD), SEMI E125.2-1224 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-1224 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1224 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA), SEMI E134-1224 Specification for Data Collection Management,

Table 8 Authorized Ballots

#	When	TF	Details
			SEMI E134.2-1224 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1224 Specification for Protocol Buffers Common Components
7420	Cycle 1-2026	EDP	Line Item Revision to SEMI E190.1-1124 - Specification for Common Data for Etch Components
7421	Cycle 1-2026	EDA	Line-Item Revision to SEMI E178-0120 Guide for EDA Freeze Version
7425	Cycle 1-2026	GEM300	Line Item Revision to SEMI E116-0324, Specification for Equipment Performance Tracking
7426	Cycle 1-2026	CDS	Line Item Revision to SEMI E191-1024 Specification for Computing Device Cybersecurity Status Reporting, and SEMI E191.1-1024 Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting
7427	Cycle 1-2026	GEM300	Line Item Revision to SEMI E172-0725, Specification for SECS Equipment Data Dictionary (SEDD)
7428	Cycle 1-2026	GEM300	Revision to Add a New Subordinate Standard: Specification for Secure High-Speed Secs Message Service (Secure-HSMS) to SEMI E37-0222 Specification for High-Speed SECS Message Services (HSMS) Generic Services

Table 9 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
6743C	GUI	Revision to SEMI E95-1101, Specification for Human Interface for Semiconductor Manufacturing Equipment	10/8/2026

Table 10 SNARF(s) Cancelled

#	TF	Title
7178	DDA	Revision to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata
7382	ESEC	Reapproval of SEMI E175-1116 - Specification for Subsystem Energy Saving Mode Communication (SESMC)

Table 11 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 12 New Action Items

Item #	Assigned to	Details
1	Albert Fuchigami (PEER Group)	Investigate EDA patents, which may be expiring soon

Table 13 Previous Meeting Action Items

Item #	Assigned to	Details
1		Obtain LOA for SEMI E54.18 - **WIP**

1 Welcome, Reminders, and Introductions

Brian Rubow called the meeting to order at 9:05. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: Required Meeting Elements March 2024

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes as written
By / 2nd:	By: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd. Second: Richard Howard / Self
Discussion:	None
Vote:	16-Y 0-N

Attachment: IC-Minutes-June-2025

3 Liaison Reports

3.1 *I&C Korea TC Chapter*

Michelle Sun (SEMI) reported for the I&C Korea TC Chapter. Of note:

- Meeting Information
    - Last Meeting
        - July 18, 2025
        - SEMI Korea, Seoul
    - Next Meeting
        - November 27, 2025
        - SEMI Korea, Seoul
- ABFI TF
    - Held an internal workshop on packaging automation trends on September 4.
    - As most members are frontend engineers, the seminar is intended to help them understand backend automation and to discuss plans and potential items for backend automation standards.

Attachment: Liaison report_KR_InC_Oct2025

3.2 *SEMI Staff Report*

Michelle Sun (SEMI) gave the SEMI Staff Report. Of note:

- 2025 & 2026 Calendar of Events

Event Name	Event Details
SEMICON WEST	Oct 07-09, 2025 Phoenix, Arizona
SEMICON EUROPA	Nov 18-21, 2025 Munich, Germany
SEMICON JAPAN	Dec 17-19, 2025 Tokyo, Japan
SEMICON KOREA	Feb 11-13, 2026 Seoul, Korea
SEMICON CHINA	March 25-27, 2026 Shanghai, China
SEMICON SOUTHEAST ASIA	May 05-07, 2026 Kuala Lumpur, Malaysia

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- SEMICON West 2025-2030
    - 2025—October 7-9 | Phoenix Convention Center | Phoenix, AZ
    - 2026—October 13-15 | Moscone Center | San Francisco, CA
    - 2027—October 12-14 | Phoenix Convention Center | Phoenix, AZ
    - 2028—October 10-12 | Moscone Center | San Francisco, CA
    - 2029—October 9-11 | Phoenix Convention Center | Phoenix, AZ
    - 2030—October 29-31 | Moscone Center | San Francisco, CA
- SEMI Global Standards Summit (GSS) 2025
    - **Date/Time**: Tuesday, October 7 | 1:30 PM to 5:30 PM | North Building, 200 Level, Room 229A
    - **Theme**: Future Standards for Connected & Sustainable Semiconductor Manufacturing
    - **Session Description**: The Global Standards Summit is a strategic forum dedicated to identifying standards-critical areas and advancing an industry-wide standardization roadmap for the next 3- and 7-year horizons. Building on the momentum of the inaugural Summit—which spotlighted essential topics such as environmental sustainability—this year's gathering continues that dialogue while expanding focus to include emerging challenges like supply chain traceability.
    - With increasing fragmentation across the global microelectronics supply chain driven by geopolitical and other disruptive forces, the need for unified standards is more critical than ever. This Summit provides a timely opportunity to convene, collaborate, and identify the standards that will address these challenges and foster greater industry alignment. We encourage you to join, engage, and help shape the future of standards.
- Workshops
    - SEMI Liquid Chemicals Analytical Workshop
        - Description: Focusing on recent advances in analytical methodology and instrumentation
        - Wednesday, October 8
        - 09:00-11:30 (North Bldg | Room 229B)
    - Enhancing Voltage Sag Immunity: SEMI F47 Standard Updates & Insights
        - Description: Delivering practical recommendations to enhance the SEMI F47 standard and increase tool resilience in future designs, with a focus on power quality conditions, equipment susceptibility, testing approaches, and mitigation strategies.
        - Wednesday, October 8
        - 14:30-16:30 (North Bldg | Room 229B)
    - Semiconductor Device Manufacturing in a Cleanroom (Best Practices to Improve Product Reliability and Yield) [SEMIU]
        - Description: Provides the fundamentals and thought processes to improve your production reliability & yield.
        - Thursday, October 9
        - 8:00 AM - 4:00 PM (North Bldg | 200 Level)
- Upcoming NA Meetings 2026

Event Name	Date/Venue
NA Winter Meeting	Feb 9-12, 2026 Full Virtual
NA Spring Meeting *(In conjunction with ASMC)*	May 11-14, 2026 Hilton Albany, New York
SEMICON West Meeting	October 12-15, 2026 San Francisco, California/USA

- SEMI Advanced Semiconductor Manufacturing Conference (ASMC)
  - SEMI's international technical conference for discussing solutions that improve the collective manufacturing expertise of the semiconductor industry.
  - Provides a platform for semiconductor professionals to network and learn the latest in the practical application of advanced manufacturing strategies and methodologies.
- Critical Dates for SEMI Standards Ballots 2026

2026	Ballot Submission Deadline	Voting Opens	Voting Closes
Cycle 1	December 16, 2025	January 7	February 6
Cycle 2	January 23	February 11	March 13
Cycle 3	March 5	March 18	April 17
Cycle 4	March 30	April 14	May 14
Cycle 5	May 8	May 27	June 26
…	**…**	**…**	**…**

- SEMI Standards Publications
  - Total Standards: 1,107
  - New Standards

Cycle	Designation	Title	Committee	Region
June 2025	SEMI M94	Specification for Silicon Carbide Engineered Substrates	Compound Semiconductor Materials	EU
July 2025	SEMI E194	Guide to Using a Liquid Particle Counter to Assess Particulate Surface Contamination on Critical Chamber Components and Coupons	Metrics	NA
September 2025	SEMI E195	Test Method Using Adhesive Replacement Substrates to Assess Particulate Surface Contamination on Critical Chamber Components	Metrics	NA
September 2025	SEMI E196	Guide for Equipment Edge Data Governance	Information & Control	TW
September 2025	SEMI M95	Test Method for Net Carrier Density and Resistivity of Silicon Epitaxial Layer by Capacitance-Voltage Measurements with an Evaporated Metal Schottky Diode	Silicon Wafer	JP
September 2025	SEMI T26	Specification for Electronic Supply Chain Traceability Using Distributed Ledger Technology	Traceability	NA

- Educational Courses under Development
  - {EDA} Everything You Need to Know about the SEMI Equipment Data Acquisition (EDA) Standards Suite
    - Objective: Introduce EDA standards, best practices for implementation, and addresses concerns about adoption through example use cases

        - Course Date: November 20, 2025, in conjunction with SEMICON Europa
        - Status: Confirmed, under development
    - {Subfab} Intro to Sub-fab Course
        - Objective: Gain a comprehensive understanding of SubFAB operations, including system components, facility layouts, environmental and sustainability considerations, organizational structure, safety and maintenance best practices, and incident-response preparedness within the semiconductor manufacturing ecosystem.
        - Course Date: Early 2026 (2 sessions, EU & Asia friendly)
        - Status: Under development
- Regulations & Procedure Manual
    - Regulations (Feb 20, 2024)
        - https://www.semi.org/sites/semi.org/files/2024-02/Standards%20Regulations%20February%2020%202024.pdf
    - Procedure Manual (July 7, 2025)
        - https://www.semi.org/sites/semi.org/files/2025-07/Procedure%20Manual%20July%2007%2C%202025%20v1.pdf
    - Noticeable updates:
        - Major revision to multiple Standards
        - New SNARF Form (July 2025)
        - Ballot checklist requirement for Revision to Primary Standard
- SNARF(s) Approved by GCS
    - 7357, New Standard: Specification for Failure Analysis Reporting
    - 7381, Revision to Add a New Subordinate Standard: Specification for Transforming Non-E142 XY Coordinates to SEMI E142-0125: Specification for Substrate Mapping

Attachment: IC_Staff_HQ Report Oct 2025 v5

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Document #7178A, Revision to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata

Voter:	Albert Fuchigami / PEER Group
Reference:	N/A
Negative:	Inconsistency on requiring Subordinate Specifications to be implemented. • Limitations 3.1 states SEMI E164 Specification does not require Subordinate Standards to be implemented in the equipment. • RQ 043 states a requirement that if the implementation supports a SEMI Standard that has its equipment metadata defined in a corresponding SEMI E164 Subordinate Standard, the implementation shall support the corresponding SEMI E164 Subordinate Standard. These two statements contradict each other; the inconsistency needs to be resolved.
Motion:	Negative is related and persuasive
By / 2nd:	By: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd. Second: Richard Howard / Self
Discussion:	None
Vote:	13-Y 0-N; motion passed

Motion:	This Document failed TC Chapter review and work will be discontinued
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Takayuki Nishimura / SCREEN
Discussion:	None
Vote:	12-Y 0-N; motion passed

4.2 Document #7344, Line Item Revision to SEMI E192-0121 – Guide for Equipment Adoption Criteria for GEM and GEM-Related Standards

4.2.1 Line Item #1: E192 Updates based on E157, E190, and E191

Voter:	Albert Fuchigami / PEER Group
Reference:	Table 8
Negative:	New row adding SEMI E190 - Comments section states 'The subordinate standards define specific data that can be published.' Currently, SEMI E190 subordinate do not do this - they define Level categories that equipment data are organized into. This sentence should be clarified or potentially removed. Perhaps just clarify that the subordinate standards define specific requirements for equipment data for a particular component type.yu7667
Motion:	Negative is related and persuasive
By / 2nd:	By: Brian Rubow / Cimetrix Incorporated Second: Fahad Golra / Agileo Automation
Discussion:	None
Vote:	13-Y 0-N; motion passed

Motion:	This Document failed TC Chapter review and will be returned to the TF for rework
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Takayuki Nishimura / SCREEN
Discussion:	None
Vote:	13-Y 0-N; motion passed

4.3 Document #7345, Line Item Revision to SEMI E90-0624 - Specification for Substrate Tracking and SEMI E90.1-0624 - Specification for SECS-II Protocol Substrate Tracking

4.3.1 Line Item #1: Report Batch Assembly and Disassembly

Voter:	Robert Flores / AMAT
Reference:	Table 8
Negative:	In Table 8, BatchAssembly event says one or more substrates are moved to the batch location, so how can BatchAssemblyState be EMPTY? Second question: if I am assembling a batch, can the state be DISASSEMBLY? Can assembling and disassembling be happening at the same time? 2. In Table 8, BatchDisassembly event says one or more substrates are moved from the batch location, so how can BatchAssemblyState be ASSEMBLED? Or ASSEMBLY? 3. Why are there events specifically calling out empty batch container arrival and departure? 4. What does it mean for an incomplete batch to arrive or depart? How is this different from BatchAssembly and BatchDisassembly events? 5. For IncompleteBatchArrived event, the description says "Either a batch that is not fully assembled has moved to the batch location." Where is the OR? 6. The state definitions of ASSEMBLY and DISASSEMBLY have an implication of the direction of substrate movement, and then these definitions do not fully align with the events pertaining to substrate arrival or removal. Is there a need to indicate the direction or should there just be a state such as PARTIAL or INCOMPLETE to indicate the location holds more than nothing but less than complete?
Motion:	Negative is related and persuasive
By / 2nd:	By: Brian Rubow / Cimetrix Incorporated Second: Takayuki Nishimura / SCREEN
Discussion:	None
Vote:	12-Y 0-N; motion passed

Motion:	This Document failed TC Chapter review and will be returned to the TF for rework
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Takayuki Nishimura / SCREEN
Discussion:	None
Vote:	13-Y 0-N; motion passed

4.4 Document #7382, Reapproval of SEMI E175-1116 - Specification for Subsystem Energy Saving Mode Communication (SESMC)

Voter:	Mitsuhiro Matsuda / Kokusai Electric
Reference:	N/A
Negative:	There exist some biased terms such as "see" and "terminate". It is a chance to address them at 5 Years Review timing. You can select this as a New Business, addressed by Type 2 editorial change (PCR), or fail this ballot and ballot as line item revision.
Motion:	Negative is related and persuasive
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Brian Rubow / Cimetrix Incorporated
Discussion:	None
Vote:	13-Y 0-N; motion passed

Motion:	This Document failed TC Chapter review and work will be discontinued
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Brian Rubow / Cimetrix Incorporated
Discussion:	None
Vote:	13-Y 0-N; motion passed

5 Subcommittee and Task Force Reports

5.1 *CDS Task Force*

Ryan Bond (Intel) reported for the CDS Task Force. Of note:

- Discussion
    - Reviewed Taiwan E187 Revision Activities
    - Reviewed SMCC SEMI E187 Compliance Guidance
    - Reviewed SMCC WG 1 Analysis and Disposition of SEMI E188
        - Previewed recommendations to SMCC Governing Council
    - Review of concept for Ballot #7231
- Requesting authorization to submit in Cycle 1 for:
    - Ballot #7231 - Revision to Add a New Subordinate Standard: Specification for Protocol Buffers for Computing Device Cybersecurity Status Reporting to Specification for Computing Device Cybersecurity Status Reporting

Attachment: CDS TF Report 20251007

5.2 *DDA Task Force*

Albert Fuchigami (PEER Group) reported for the DDA Task Force. Of note:

- EDA ‘Core’ Standards Update

- Planning another ballot cycle to address changes around metadata definitions supporting multiple SECS identifiers, supporting a new SEMI E132 Security Certificate Changed notification message and addressing issues raised by TF members.
- Getting close to having changes integrated to start considering EDA Freeze 3 Release Candidates.

- SEMI E164
  - Planning new SNARF to take advantage of SEMI Regs changes to ballot major revisions against multiple related Standards together. Look to update SEMI E164 and create new SEMI E164 Subordinate Standards for E30, E40 and E87 content at the same time. This will help ensure changes to SEMI E164 Primary Standards have the infrastructure and requirements to support the new Subordinate Standards being created.
  - SEMI E164 Subordinate Standards are not part of the Freeze 3 definition.

Attachment: DDA TF Report - SEMICON West 2025_Rev 1.0

5.3 *GUI Task Force*

Tami Tracey (Cimetrix) reported for the GUI Task Force. Of note:

- The task force reviewed Ballot R6743C and agreed to issue Ratification Ballot to address voter comments.
- At the same time, the task force leader asked to extend the SNARF if the Ratification Ballot fails.

Motion:	Approve the SNARF Extension 6743
By / 2nd:	By: Tami Tracey / Cimetrix Incorporated Second: Bert Mueller / Kontron-AIS GmbH
Discussion:	None
Vote:	15-Y 0-N; motion passed

Attachment: GUI TF Report - 2025-10-08

5.4 *PCS Task Force*

James Moyne (AMAT/UMICH) reported for the PCS Task Force. Of note:

- TFOF proposal: Digital Twin for Manufacturing Task Force (DTM)
- PCS motion in support of creation of this TF

Attachment: PCS-TF-report20251006

5.5 *Sensor Bus Task Force*

Dan Judd (Arlington Laboratory) reported for the Sensor Bus Task Force. Of note:

- Common model, SDM documents up to date
- Non compliant NCS documents withdrawn or updated for biased terms and compliance with SEMI E54
- Dan Judd is stepping down as leader of the Sensor Bus Task Force (upon close of this weeks meetings)

Attachment: SBTF-Report-Oct-2025-v1.0

5.6 *ABFI Task Force*

Brian Rubow (PDF Solutions) reported for the ABFI. Of note:

- Discussion of SEMI E142.2 Collection Event
  - Negative Text: Section 8.2 Well-Known Variables and Section 8.3 Well-Known Collection Events E142.4 requires at least one collection event E142SubstrateMapDataReady, and data variables ItemType, ItemID, ItemLength and ItemVersion. I disagree with several statements in the proposed 8.3.2.1 that "the collection is not defined in this Standard" and the implication that another collection event in another standard can be substituted for this collection event. If we are going to have well-knowns in E142.4, we need to figure out to

describe that for this collection event. I recognize that there might be more than one collection event. Perhaps the collection event definition itself needs improvement, but this is not a suitable solution.

- Considerations
  - Explicitly define collection event E142SubstrateMapDataReady. It is an implementation detail when the event is raised. This means there could be two events triggered for the same trigger – say event E142SubstrateMapDataReady and events indicating the process job is complete.
  - Use Case scenario - Could have one event triggered in multiple situations, or one event per situation Could support both and have a DV to indicate the source.
  - Example 1 – all Chambers on the Tool are Etch – all have the same trigger condition. Could be one event with DV indicating which chamber.
  - Example 2 – CH A and B are Etch, CH C and D are Deposition. Could have same event for Etch chamber, and a different event for Deposition chamber (different events)
  - WKN could use the template approach to identify the trigger condition number. e.g. E142.E142SubstrateMapDataReady and E142.E142SubstrateMapDataReady.<#>
- Discussion
  - Don't want to hijack other event definitions (e.g. job complete) to say Substrate Map Ready
  - Q – Do we want to extend WKN to report multiple – comma separated?
  - Q – how will industry adopt it? Host systems may already use one event for multiple purposes.
  - Want to have all events defined in SEMI Standards have specific meanings. Ambiguous between supplier can cause confusion. Make it easier to implement and test.
  - Q – we're saying there' an event, but not dictating when the event is raised – when is usbstrate map ready expected to be sent.
- Continue discussion in future ABFI meetings.
- Decided to fail 7380 and resubmit in the future – include addressing Collection Event E142SubstrateMapDataReady.

Attachment: SEMICON West 2025_ABFI_Ballot Adjudication_Rev 1.1

5.7 *GEM300 Task Force*

Brian Rubow (PDF Solutions) reported for the GEM300 Task Force. Of note:

- Adjudication
- Reviewed the three proposed SNARFs
- Long discussion about E90 batch loading/unloading reporting. Unable to reach a consensus on how to proceed. There are three proposed approaches to strategy.

Attachment: SEMI NA-ICC-GEM300-TF Report Fall 2025

6 New Business

6.1 *New Task Force: Digital Twins in Manufacturing*

James Moyne (AMAT/UMICH) addressed the committee on this topic.

Motion:	Approve the Digital Twin TFOF
By / 2nd:	By: James Moyne / Applied Materials, Inc. Second: Chris Maloney / Intel Corporation
Discussion:	None
Vote:	14-Y 0-N; motion passed

Attachment: DT-TFOF_Sept2024-Template-V2

7 Next Meeting and Adjournment

The next meeting is scheduled for Wednesday, February 11, 2026, via Web Conference. See http://www.semi.org/standards-events for the current list of events.

Monday, February 9, 2026
- 9:00-10:00 – NA I&C Leadership Meeting
- 10:00-11:00 – ABFI Task Force
- 11:00-12:00 – ESEC Task Force
- 13:00-16:00 – GEM300 Task Force
- 16:00-17:30 – EDP Task Force

Tuesday, February 10, 2026
- 8:00-10:00 – GUI Task Force
- 10:00-12:00 – Digital Twins + PCS Task Force
- 13:00-16:00 – DDA Task Force
- 16:00-17:30 – CDS Task Force

Wednesday, February 11, 2026
- 9:00-12:00, 13:00-16:00 – I&C NA TC Chapter Meeting

Adjournment: 3:47.

Respectfully submitted by:

Michelle Sun
Coordinator
SEMI North America
Phone: 408.943.7982
Email: msun@semi.org

Minutes tentatively approved by:

<Name> (<Company>), Co-chair	<Date approved>
<Name> (<Company>), Co-chair	<Date approved>

Table 14 Index of Available Attachments[#1]

Title	*Title*
Required Meeting Elements March 2024	CDS TF Report 20251007
IC-Minutes-June-2025	DDA TF Report - SEMICON West 2025_Rev 1.0
Liaison report_KR_InC_Oct2025	GUI TF Report - 2025-10-08
IC_Staff_HQ Report Oct 2025 v5	PCS-TF-report20251006
SBTF-Report-Oct-2025-v1.0	SEMICON West 2025_ABFI_Ballot Adjudication_Rev 1.1
SEMI NA-ICC-GEM300-TF Report Fall 2025	DT-TFOF_Sept2024-Template-V2
SNARF CDS LI E191	SNARF DDA E178
SNARF DDA LI EDA Standards	SNARF EDP E190.1 V7
SNARF GEM 300 E116	SNARF Revision E164
SNARF_LIRev_E172_October 2025_Rev 1.1	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.